# For Disc Type Wet Extrusion Process
# 濕式擠出成型用

## Temperature Compensation Type

| Designation | Electric Properties | | | Reference Code | | Reference Firing Temperature, ℃ | Addition of Low Melt Additive |
|---|---|---|---|---|---|---|---|
| | K-value at 1MHz | Q Factor Min. | I.R. Min. MΩ | JIS | EIA | | |
| NPO-10 | 10.0±1.0 | 2000 | $10^5$ | CH | COH | 1320±10 | - |
| NPO-13 | 13.0±1.0 | 3000 | $10^5$ | CG | COG | 1330±10 | - |
| NPO-20 | 23.0±1.0 | 3000 | $10^5$ | CG | COG | 1330±10 | - |
| NPO-40 | 44.0±1.5 | 3000 | $10^5$ | CG | COG | 1210±10 | - |
| NPO-110 | 107±3 | 3000 | $10^5$ | CG | COG | 1270±10 | O |
| N750 | 100±15 | 2000 | $10^5$ | UH | U2H | 1230±10 | - |
| SL-330 | 325±15 | 2000 | $10^5$ | SL | - | 1355±10 | O |

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## High-K Type

| Designation | Electric Properties | | | Reference Code | | Reference Firing Temperature, ℃ | Addition of Low Melt Additive |
|---|---|---|---|---|---|---|---|
| | K-value at 25℃ | D.F. Max.% | I.R. Min. Ω | JIS | EIA | | |
| Z5U | 11500±1500 | 1.0 | $10^4$ | ZE | Z5U | 1360±10 | - |
| Z5V | 20000±3000 | 1.0 | $10^4$ | ZF | Z5V | 1380±10 | - |
| Y5U | 8500±850 | 1.0 | $10^4$ | YE | Y5U | 1330±10 | - |
| Y5E | 1710±100 | 1.0 | $10^4$ | YA | Y5E | 1255±10 | O |
| Y5P | 3650±200 | 1.5 | $10^4$ | YB | Y5P | 1390±10 | O |
| Y5V | 15500±2000 | 1.0 | $10^4$ | YF | Y5V | 1380±10 | - |
| Y5P-XHT | 3650±350 | 2.0 | $10^4$ | YB | Y5P | 1390±10 | O |
| X7R | 3300±330 | 2.0 | $10^4$ | | X7R | 1355±10 | O |

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## Semi-conductive Type

| Designation | Electric Properties | | | Reference Code | | Reference Firing Temperature, ℃ | Addition of Low Melt Additive |
|---|---|---|---|---|---|---|---|
| | K-value at 25℃ | D.F.Max.% | I.R. Min. Ω | JIS | EIA | | |
| SBL— Y5V | 12000±1000 | 0.45 | $10^4$ | YF | Y5V | 1300±10 | - |
| SBL— Y5U | 8500±500 | 0.50 | $10^4$ | YE | Y5U | 1325±10 | - |